

PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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Takeshi TOKUYAMA	06/02/2008
Kinya NAKATSU	06/02/2008
Ryuichi SAITO	06/02/2008
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State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12060629
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OP \$40.00 12060629

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

POWER SEMICONDUCTOR MODULE FOR INVERTER CIRCUIT SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (發明者フルネームサイン)	Date Signed (署名日)
1) Takeshi TOKUYAMA <u>Takeshi Tokuyama</u>	6/8/2008 TT 6/2/2008 6/2/2008
2) Kinya NAKATSU <u>Kinya Nakatsu</u>	6/2/2008
3) Ryuichi SAITO <u>Ryuichi Saito</u>	6/2/2008
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____